(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
18 December 2008 (18.12.2008)

PCT

(10) International Publication Number
WO 2008/151649 A1

(51) International Patent Classification:
H01L 23/544 (2006.01)

(21) International Application Number:
PCT/EP2007/005212

(22) International Filing Date: 13 June 2007 (13.06.2007)

(25) Filing Language: English

(26) Publication Language: English

(71) Applicant *(for all designated States except US)*: **CONERGY AG** [DE/DE]; Anckelmannsplatz 1, 20537 Hamburg (DE).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **RICHTER, André** [DE/DE]; Am Büsenbach 60, 21256 Handeloh-Wörme (DE). **KRENZIN, Marcel** [DE/DE]; Pölitzer Strasse 5, 12621 Berlin (DE). **MOECKE, Jens** [CH/CH]; Breita 852, 1713 ST. Antoni (CH).

(74) Agent: **BIRKEN, Lars**; Eisenführ, Speiser & Partner, Zippelhaus 5, 20457 Hamburg (DE).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*

(54) **Title:** METHOD FOR MARKING WAFERS

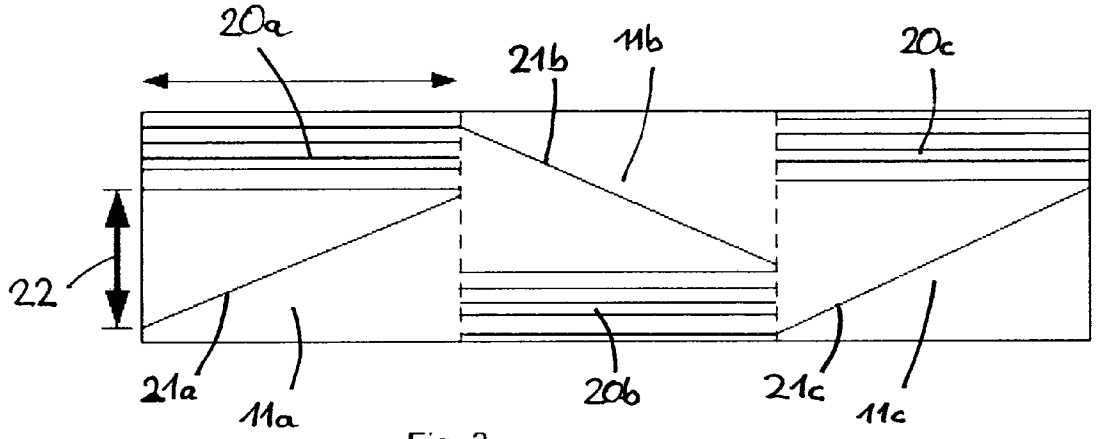


Fig. 3

(57) **Abstract:** The invention relates to a method for marking wafers, in particular wafers for solar cell production: The method comprises the steps of manufacturing a position line (21a, 21b, 21c) on a peripheral surface of a silicon ingot or column, the ingot or column extending in an axial direction and having a longitudinal axis in the axial direction, wherein the position line extends in the axial direction along substantially the whole ingot or column and is inclined with respect to the longitudinal axis. By this position line it is possible to determine the position of a wafer cut from the ingot or column within the ingot or column, respectively. Further, an individual identification pattern (20a, 20b, 20c) of lines on the peripheral surface of the silicon ingot or column is manufactured, the individual identification pattern of lines extending in axial direction over substantially the whole ingot or column and providing an individual coding which allows to identify the silicon ingot or column.

WO 2008/151649 A1